

Clean Version of Amended Claims

1. (Amended) A flex-print circuit (FPC) attached to at least one bonding pad on a suspension of a head gimbal assembly in a hard disk drive using anisotropic conductive adhesive, comprising:

a base film;

a conductive layer situated below the base film;

an overcoat layer comprising at least two sections situated below the conductive layer, a bottom surface of each section overlapping partially and to be pressed onto a top surface of the bonding pad; and

a conductive structure forming an electric conduit between the conductive layer and the at least one bonding pad, said anisotropic conductive adhesive being disposed at least partially surrounding the conductive structure for bonding the FPC to the at least one bonding pad.

21. (Amended) A flex-print circuit (FPC) attached to a bonding pad, comprising:

a conductive layer, in said flex print circuit, bonded to the bonding pad using anisotropic conductive adhesive; and

a conductive bump lodged between the conductive layer and the bonding pad.

27. (Amended) A bonding device adapted for attachment to a bonding pad with an anisotropic conductive adhesive, the bonding device comprising:

a base film;

a conductive layer having a first side and a second side wherein a first side of the conductive layer is attached to the base film;

an overcoat layer attached to a first portion of a second side of the conductive layer; and
a conductive element attached to a second portion of the second side of the conductive layer
wherein the conductive element is adapted to form an electrical conduit between the conductive
layer and the attached bonding pad, and the overcoat layer is to press against said bonding pad.

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